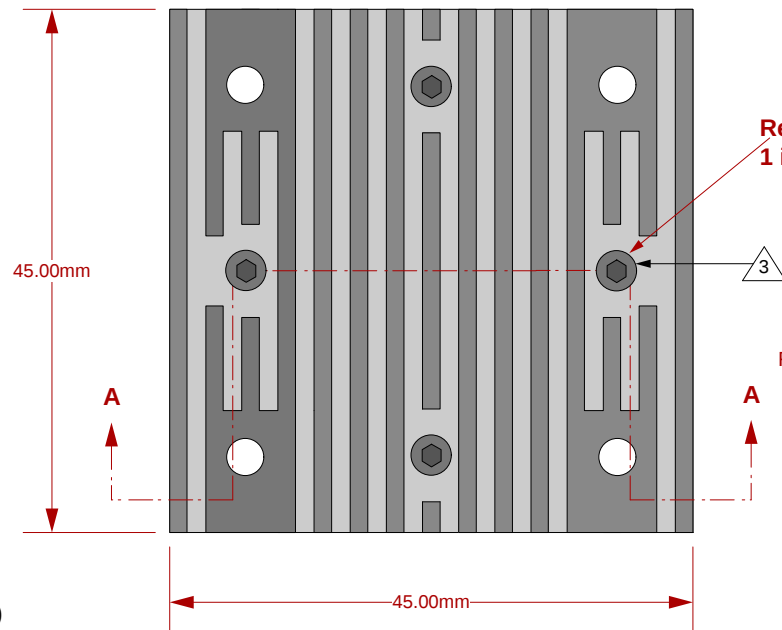
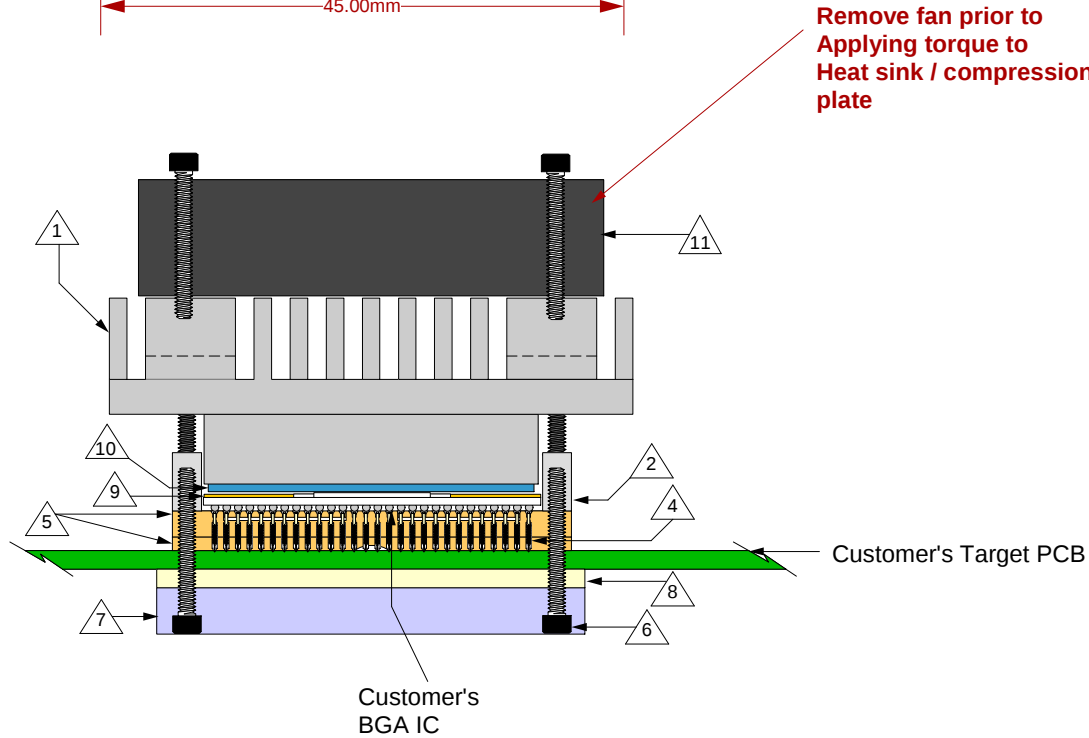


SBT BGA Socket - Direct mount, solderless



Top View:
(fan removed)



Side View
(Section AA)

Features

- Directly mounts to target PCB (needs tooling holes) with hardware.
- High speed, reliable SBT Pin connection
- Minimum real estate required
- Compression plate distributes forces evenly
- Easily removable swivel socket lid

- | | |
|----|--|
| 1 | Socket Lid/ Heat sink: Ni plated Aluminum. |
| 2 | Socket base: Ni plated Aluminum.
Thickness = 5mm. |
| 3 | Compression screw: Socket head cap, alloy steel with black oxide finish, 0-80 fine thread , 7.94mm long. |
| 4 | SBT pin: Stamped contact BeCu, Au plated
Spring: SS, Au plated |
| 5 | Pin Guide: Ceramic Filled Peek |
| 6 | Socket base screw: Socket head cap, alloy steel with black oxide finish, 0-80 fine thread , 15.875mm long. |
| 7 | Backing Plate: Ni plated Aluminum.
Thickness = 4mm. |
| 8 | Insulation Plate: FR4, Thickness = 1.59mm. |
| 9 | IC Frame: Ultem |
| 10 | Gap Pad |
| 11 | Fan: 40x40x10mm |

SBT-BGA-6019 Drawing

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Tele: (952) 229-8200
www.ironwoodelectronics.com

Status: Released

Scale: -

Rev: A

Drawing: E Smolentseva

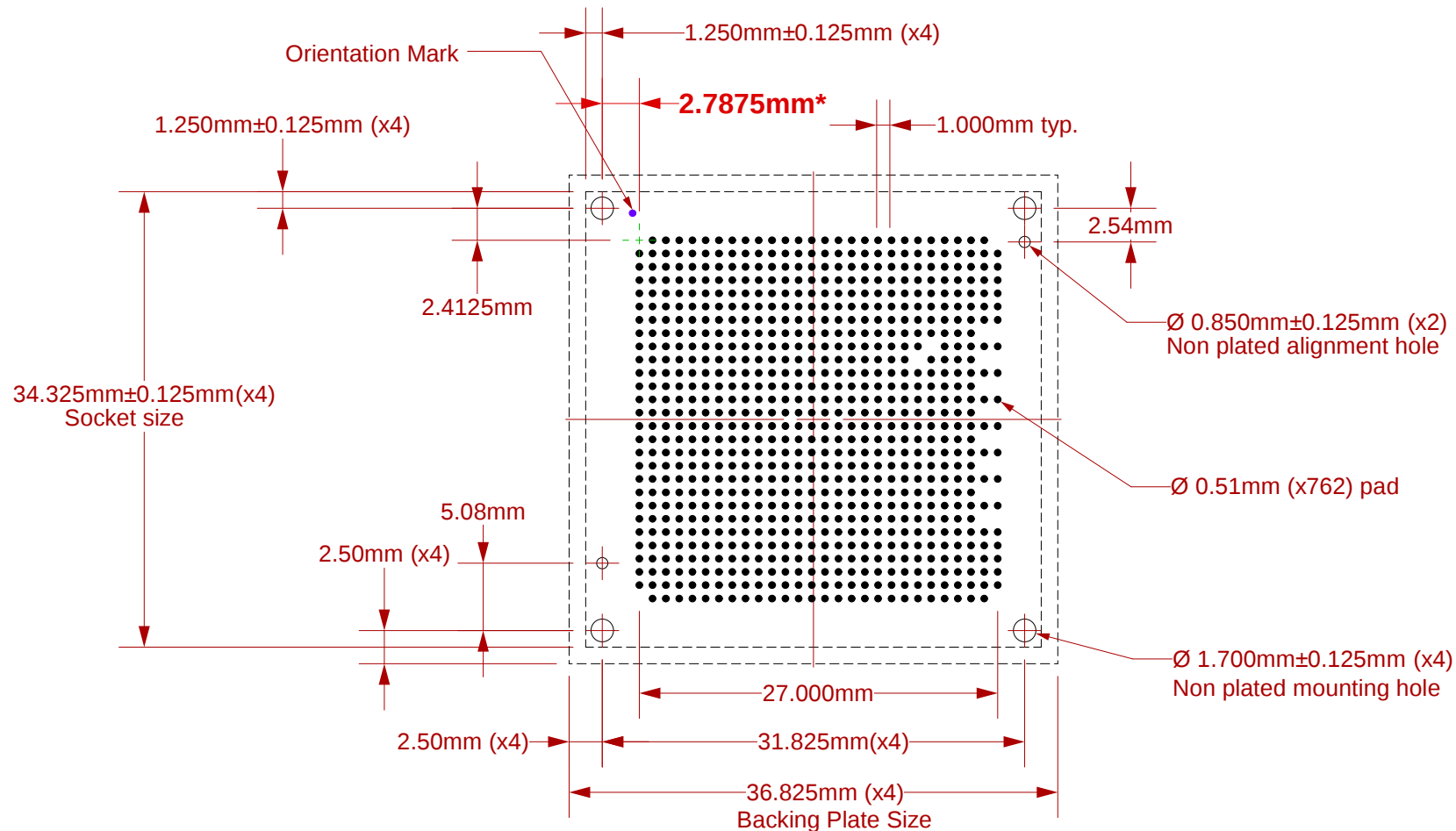
Date: 09/08/2012

File: SBT-BGA-6019 Dwg.mcd

Modified:

All tolerances: $\pm 0.125\text{mm}$ (unless stated otherwise). Materials and specifications are subject to change without notice.

***Note: BGA pattern is not symmetrical with respect to the mounting holes. It is offset 0.375mm to the right of the tooling holes.**



Target PCB Recommendations

Total thickness: 3.175mm min.

Plating: Gold or Solder finish

PCB Pad height: Same or higher than solder mask

NOTE: Steel backing plate may be required based on end user's application

Recommended PCB Layout Tolerances: ±0.025mm [±0.001"] unless stated otherwise.

SBT-BGA-6019 Drawing

Status: Released

Scale: -

Rev: A



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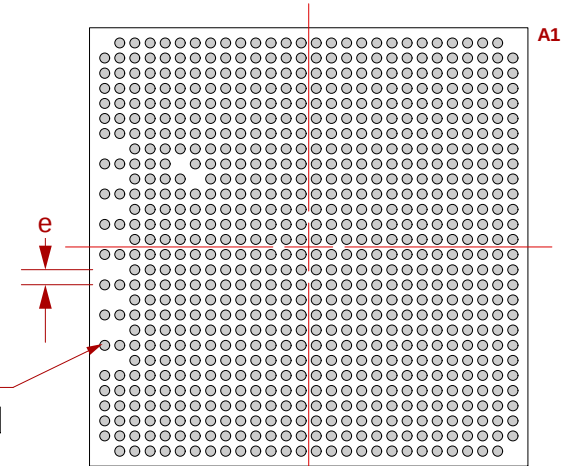
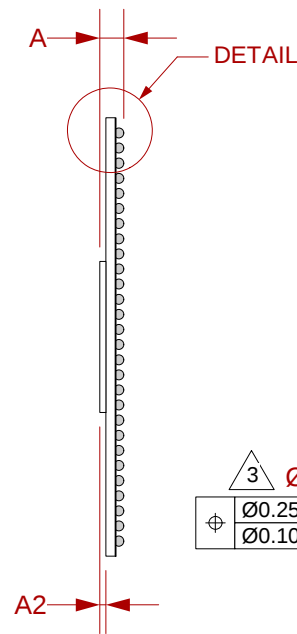
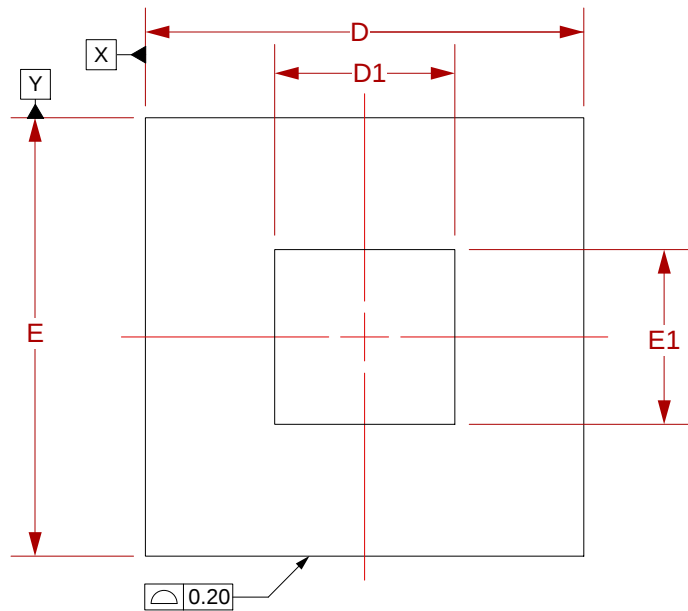
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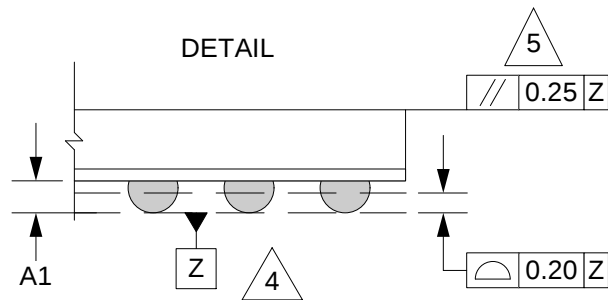
File: SBT-BGA-6019 Dwg.mcd

Modified:

Compatible BGA Spec



Ironwood Package Code: BGA762A



1. Dimensions are in millimeters.
2. Interpret dimensions and tolerances per ASME Y14.5M-1994.
3. Dimension b is measured at the maximum solder ball diameter, parallel to datum plane Z.
4. Datum Z (seating plane) is defined by the spherical crowns of the solder balls.
5. Parallelism measurement shall exclude any effect of mark on top surface of package.

DIM	MIN	MAX
A	1.41	1.69
A1	0.40	0.6
A2	0.36	0.42
b	0.5	0.7
D1	12.09	
E1	11.88	
D	29.0 BSC	
E	29.0 BSC	
e	1.00 BSC	

Array 28 x 28

SBT-BGA-6019 Drawing

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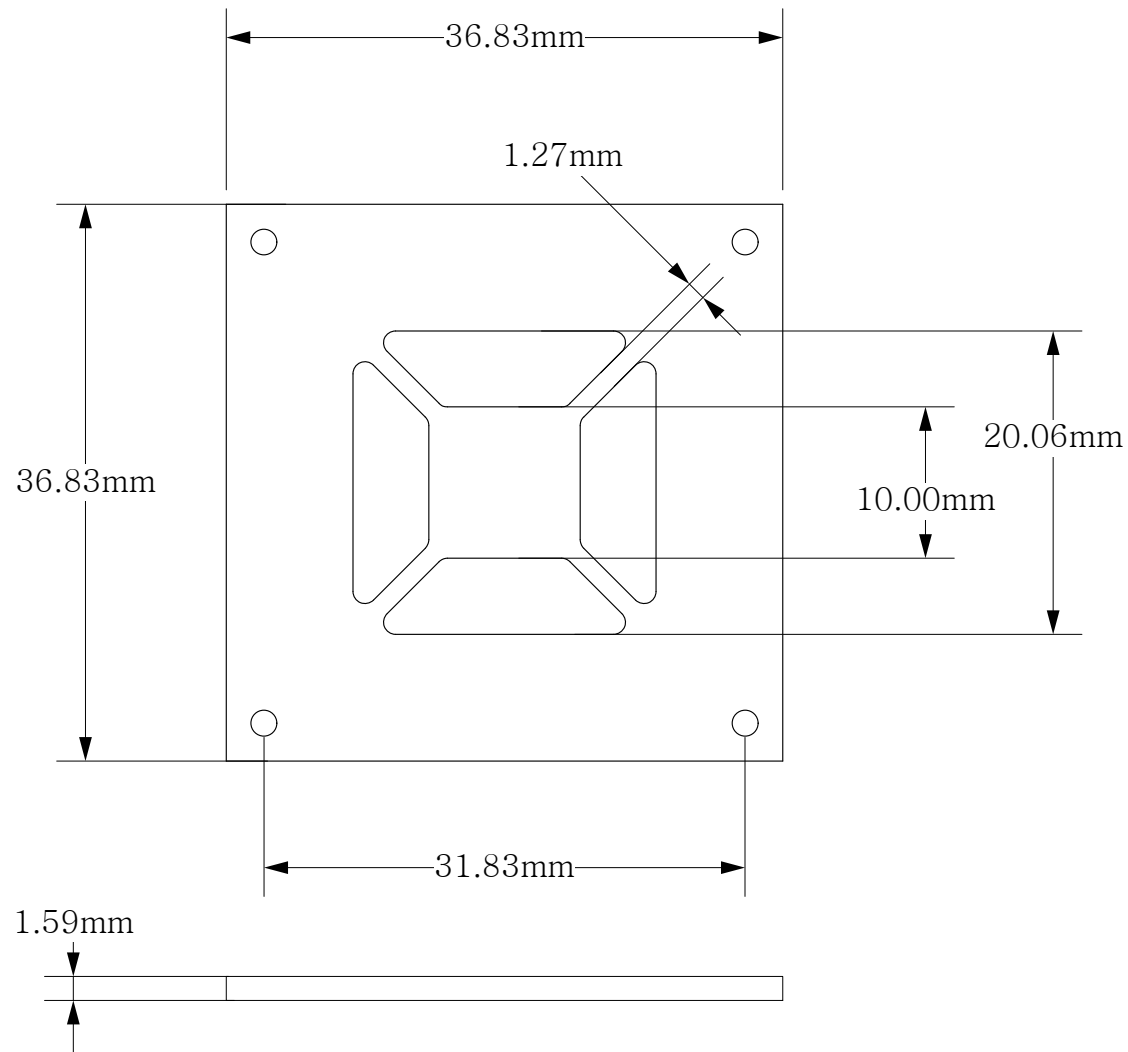
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Modified:

Insulation Plate



SBT-BGA-6019 Drawing

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